



In-line X-ray and Optical Inspection for Electronic Assemblies



AOI/AXI

Leading Edge Inspection Technology

Optical and Simultaneous 2-D, 2.5-D and 3-D X-ray Inspection

Simultaneous optical and X-ray inspection

3-D X-ray inspection with selectable resolutions of 5, 7 or 10 μm per pixel

High performance, tomosynthesisbased 3-D X-ray back calculation

Optical inspection with 11.7 and 23.4 µm resolution

Short handling time

Compact housing dimensions: Only 1.3 m (X7056RS) or 1.7 m (X7056RL) wide

Worldwide competent service: on site, hotline and remote support

Viscom Support Website

Reduce false alarms with AXI-OnDemand

New electronic products are arriving to the market today at increasingly rapid cycles. Time allowed for development and modeling is getting shorter, as demands for top quality rise. The automatic optical inspection (AOI) of printed circuit boards is accepted worldwide. Manufacturers with miniaturized components such as BGAs, μ BGAs, CSPs and FlipChips require a positive and cost-effective quality inspection process that also locates concealed defects – with extensive inspection depth and high throughput.

AOI – AXI compared:



Only recognizable with AOI: OCR application



Only recognizable with AOI: SOIC polarity



Only recognizable with AXI: BGA bridge



Only recognizable with AXI: Defect in THT connection

X7056 – The new AXI standard, fast and flexible

The core of X-ray technology – a high performance closed **microfocus X-ray tube** provides selectable resolutions of 5, 7 or 10 µm per pixel for X-ray inspections. Depending on the application, 3-D, 2.5-D or 2-D X-ray technologies are employed to achieve the highest inspection depth and short cycle times.

The 3-D results are based on tomosynthesis and facilitate an **outstanding image quality**. Thus, complex overlap on printed circuit boards populated on both sides can be resolved and easy-to-analyze features generated. Due to the integration of the optical **8M camera technology** the system offers additionally the high inspection depth of the Viscom AOI systems at comparable throughput. Within the **OnDemandHR function** the AOI resolution can be flexibly switched over from 23.4 to 11.7 μ m/pixel with the full image field size. In the angled view, a range of 16.1 μ m/pixel to 8.05 μ m/pixel is possible. In addition, the inspection system provides the option of **color evaluation**.

With its **simultaneous optical and X-ray inspection**, the high performance combo-system sets a new standard in quality assurance. Through this simultaneous inspection **very fast in-spection** and **minimum handling times** are achieved. The system is **fully modular**, so it can be used as a combined system or as a pure AXI system. These different inspection concepts display the ultimate in flexibility that can be directly employed to customer requirements.

EasyPro presents a user interface that is concise and convenient in both AOI mode and X-ray operation. Program generation and optimization can be conducted quickly and easily, and is compatible with existing Viscom systems. As an option, high performance **SPC software** with a variety of filtering functions is available for process control and optimization.

Viscom's automatic analysis software algorithms, which include intelligent analyses for ball grid arrays (BGAs) and FlipChips, and for standard solder joints (voiding calculation), are also available for this system.

2-D X-ray – 3-D X-ray compared:



2-D image of a BGA: Structures from the rear side are present in the image



3-D image of a BGA: Sectioned image without interfering structures

Technical Specifications



	X7056 variants		AXI	AOXI
	Inspection concept	2-D-AXI	3-D-AXI	2-D-AXI + AOI 3-D-AXI + AOI
X-ray technology				
	X-ray tube	Closed X-ra	y tube	
	High voltage	60 - 130 kV		
	Tube current	50 - 300 µA		
	Detector			or, 12 bit grayscale depth
	Pixel size		n per pixel, switchable	•
	Z-axis adjustment	Powered Z-axis tube adjustment		
	X-ray cabinet	Designed as a full protection cabinet according to the RöV (German X-ray regulations) dated 30.04.2003 and US standard 21CFR \$1020-40 and further international standards, leakage radiation < 1µSv/h		
Optical camera technology				
	Camera module 8M	8M technolo	ogy with OnDemandHl	3
	Field of view	57.6 x 43.5 r	nm (2.3" x 1.7")	
	Number of mega pixel cameras	2 - 12		
	Resolution (orthogonal)	23.4 µm, 11.	7 µm (switchable)	
	Resolution (angled view)	16.1 µm, 8.0)5 µm (switchable)	
Software				
	User interface	Viscom Eas	yPro/vVision ready	
	Verification station		RAN/vVerify ready	
	SPC	Viscom SPC	c (statistical process co	ontrol), open interface (optional)
	Remote diagnosis	Viscom SRC	C (software remote con	trol) (optional)
	Off-line programming	Viscom PST	34 (external Programm	ning Station) (optional)
	Systematic Defect Analysis and	Viscom PDC	C (ProcessDataControl)	,
	Continuous System Monitoring	TCM (Techn	icalChainManagemen	t)
System computer				
	Operating system	Windows®		
	Processor	Intel [®] Core [*]	™ i7	
PCB handling				
	PCB dimensions*	X7056RS: 4	50 x 350 mm (18.0" x 1	3.8") (L x W)
			10 x 508 mm (24.0" x 2	0.0") (L x W)
	Transport height		nm ± 20 mm	
	Width adjustment	Automatic v		
	Handling unit			free high speed drives
	Dual track operation		th external PCB modul	es
	PCB clamping	During insp		
	PCB edge clearance	3 mm (0.12		
	Upper transport clearance	35 mm (1.38	•	
	Lower transport clearance	50 mm (1.97	·)	
Inspection speed				
	AOI	Typical 20 -		
	AXI	Depends or	application	
Other system data				
	Interfaces	SMEMA, SV	/70, customer specific	
	Power requirements			quest, 3 phases, 50/60 Hz, 5 kW
	System dimensions			6 mm (49.8" x 86.0" x 64.0") (W x D x
		X7056RL: Ap	prox. 1738 x 3166 x 1626	6 mm (68.4" x 124.6" x 64.0") (W x D x
	Line integration dimensions		25 mm (1.0"), X7056RL:	
	Weight		oprox. 2500 kg (5511 lbs	



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